

# Application of ERBS analysis on O diffusion in TiO<sub>2</sub> films

G. G. Marmitt\*

S. K. Nandi<sup>†</sup>, D. K. Venkatachalam<sup>†</sup>, R. G. Elliman<sup>†</sup>,  
M. Vos<sup>†</sup> and P. L. Grande<sup>\*</sup>



\*Universidade Federal do Rio Grande do Sul (UFRGS), Brazil  
†The Australian National University (ANU), Australia

# Outline

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1. Introduction
  2. ERBS analysis
  3. O diffusion in TiO<sub>2</sub>
  4. Conclusions
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# 1. Introduction

ERBS system

# Materials characterization

**Table 1.1** Imaging and analysis techniques employing electron, ion, and photon beams, with estimates of the achievable spatial resolution

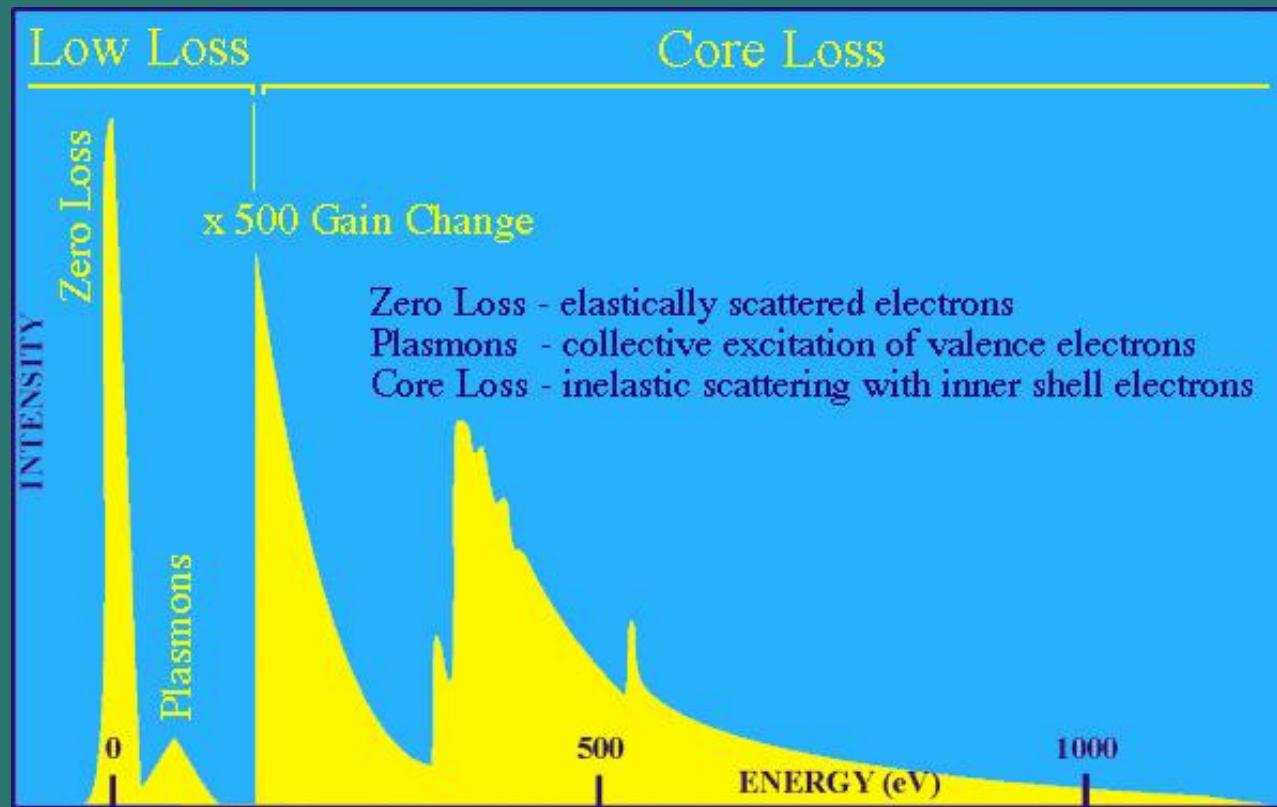
Incident beam	Detected signal	Examples	Resolution (nm)
Electron	Electron	Electron microscopy (TEM, STEM)	0.1
		Electron diffraction (SAED, CBED)	10–1000
		Electron energy-loss spectroscopy (EELS)	<1
		Auger electron spectroscopy (AES)	~2
	Photon	X-ray emission spectroscopy (XES)	2–10
		Cathodoluminescence (CL)	
Ion	Ion	Rutherford backscattering spectroscopy (RBS)	1000
		Secondary ion mass spectrometry (SIMS)	50
		Local electrode atom probe (LEAP)	0.1
Photon	Photon	Proton-induced x-ray emission (PIXE)	500
		X-ray diffraction (XRD)	30
		X-ray absorption spectroscopy (XAS)	20
	Electron	X-ray fluorescence spectroscopy (XRF)	
		X-ray photoelectron spectroscopy (XPS)	5–10
		Ultraviolet photoelectron spectroscopy (UPS)	1000
	Ion	Photoelectron microscopy (PEM or PEEM)	0.5
		Laser microprobe mass analysis (LAMMA)	1000

# Materials characterization

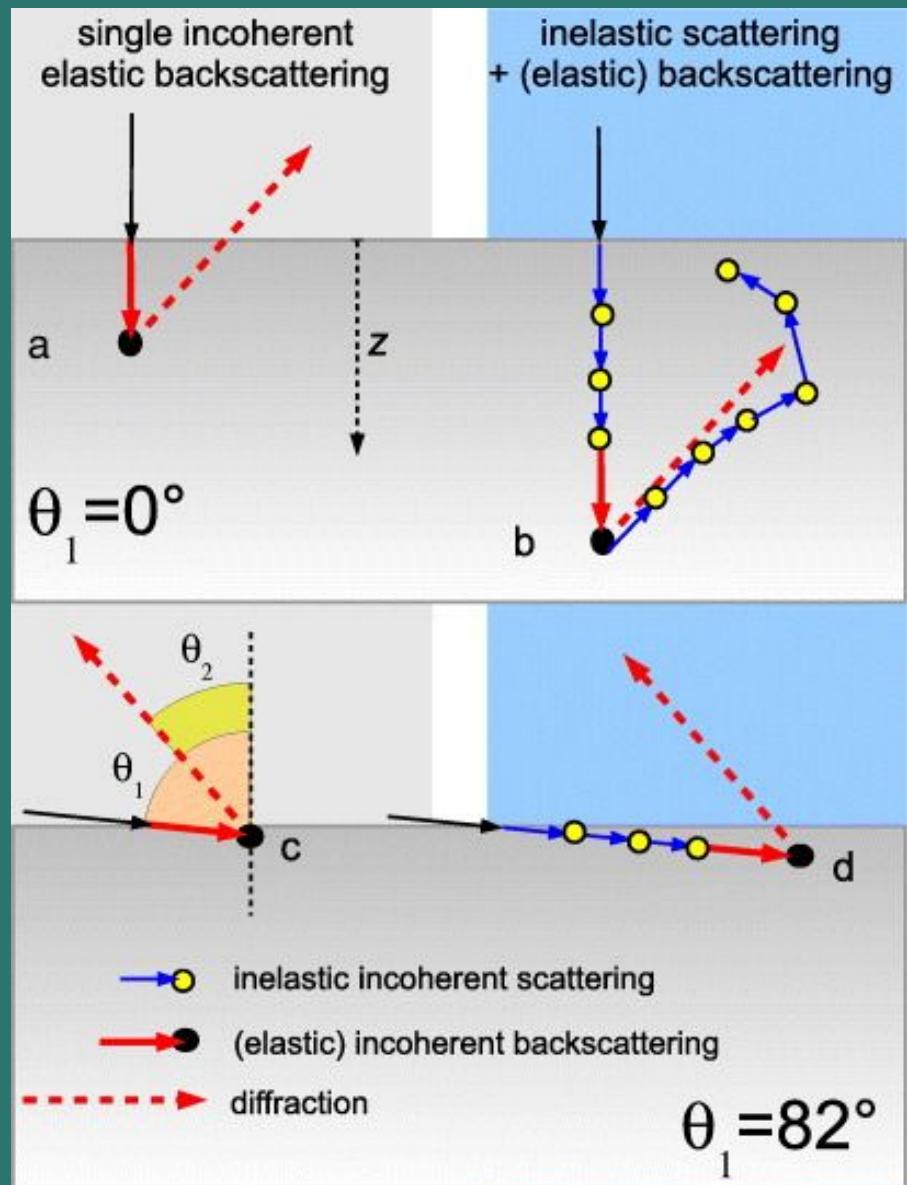
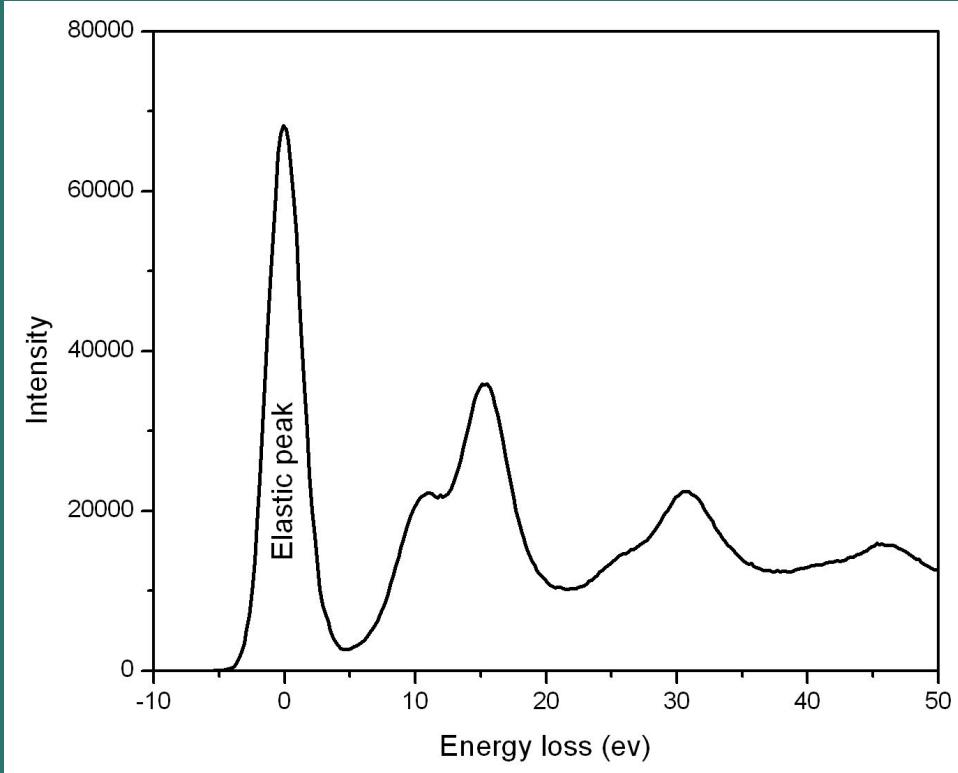
**Table 1.1** Imaging and analysis techniques employing electron, ion, and photon beams, with estimates of the achievable spatial resolution

Incident beam	Detected signal	Examples	Resolution (nm)
Electron	Electron	Electron microscopy (TEM, STEM) Electron diffraction (SAED, CBED) Electron energy-loss spectroscopy (EELS)	0.1 10–1000 <1
	Photon	X-ray emission spectroscopy (XES) Cathodoluminescence (CL)	2–10
	Ion	Rutherford backscattering spectroscopy (RBS) Secondary ion mass spectrometry (SIMS)	1000 50
Photon	Ion	Local electrode atom probe (LEAP)	0.1
	Photon	Proton-induced x-ray emission (PIXE)	500
	Photon	X-ray diffraction (XRD)	30
	Electron	X-ray absorption spectroscopy (XAS) X-ray fluorescence spectroscopy (XRF) X-ray photoelectron spectroscopy (XPS) Ultraviolet photoelectron spectroscopy (UPS)	20 5–10 1000
	Ion	Photoelectron microscopy (PEM or PEEM) Laser microprobe mass analysis (LAMMA)	0.5 1000

# EELS spectrum



# Backscattering EELS



# Elastic peak

- Kinematic factor

$$E = E_0 - E_r = kE_0$$

$$k \approx 0.9999$$

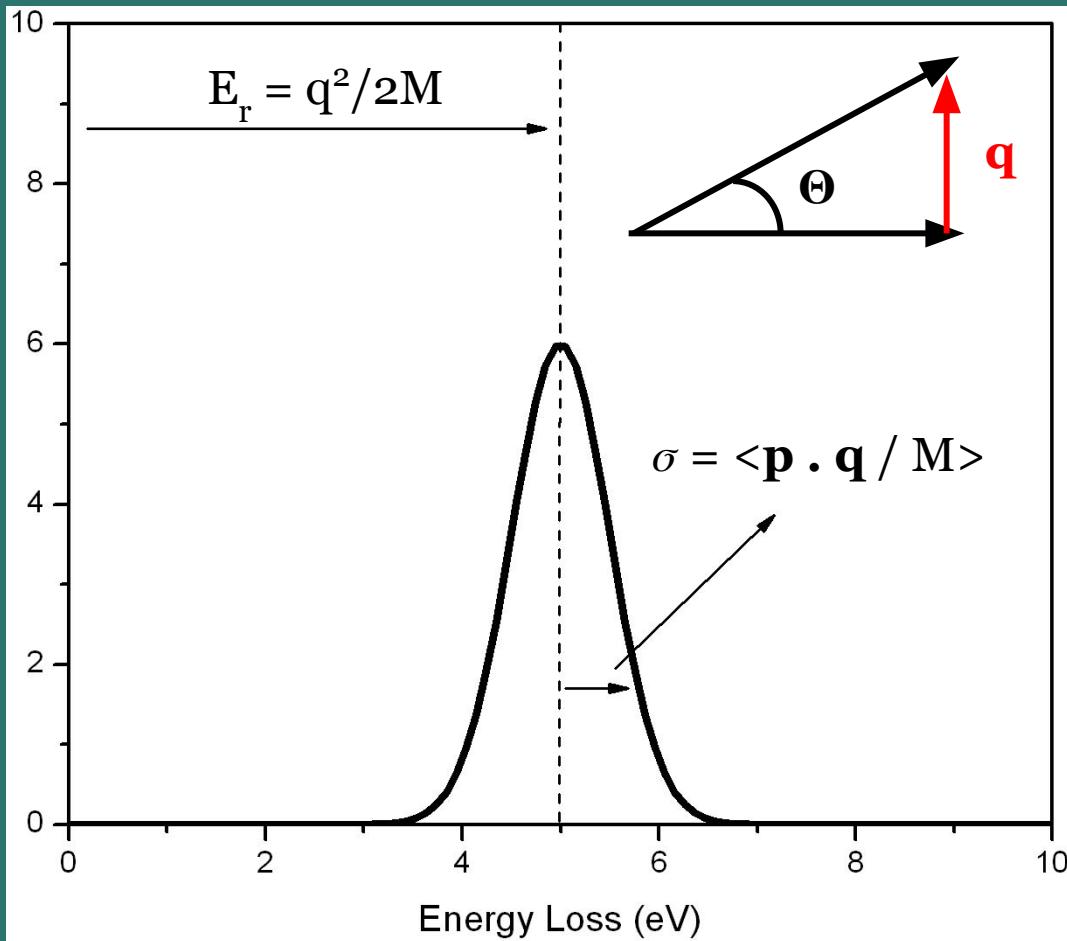
- For isotropic systems

$$\sigma = \left( \frac{4}{3} E_{kin} E_r \right)^{\frac{1}{2}}$$

- Gaussian peak

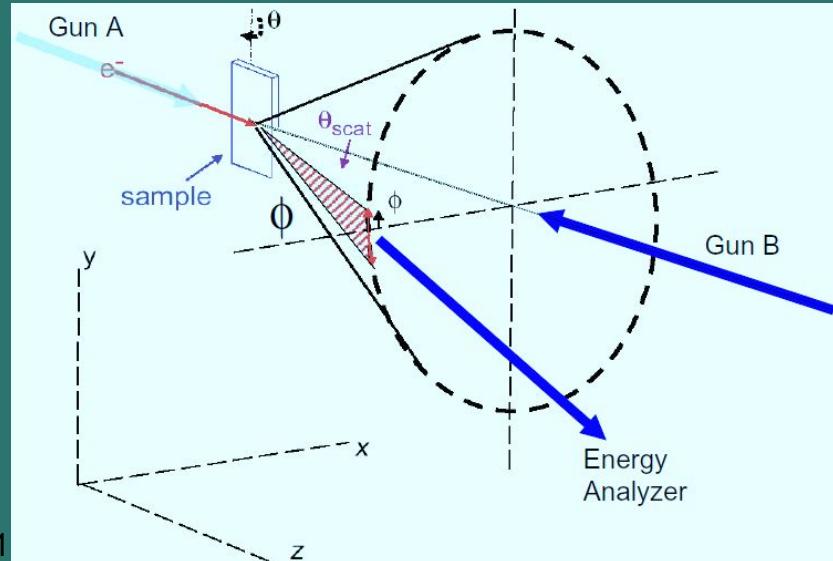
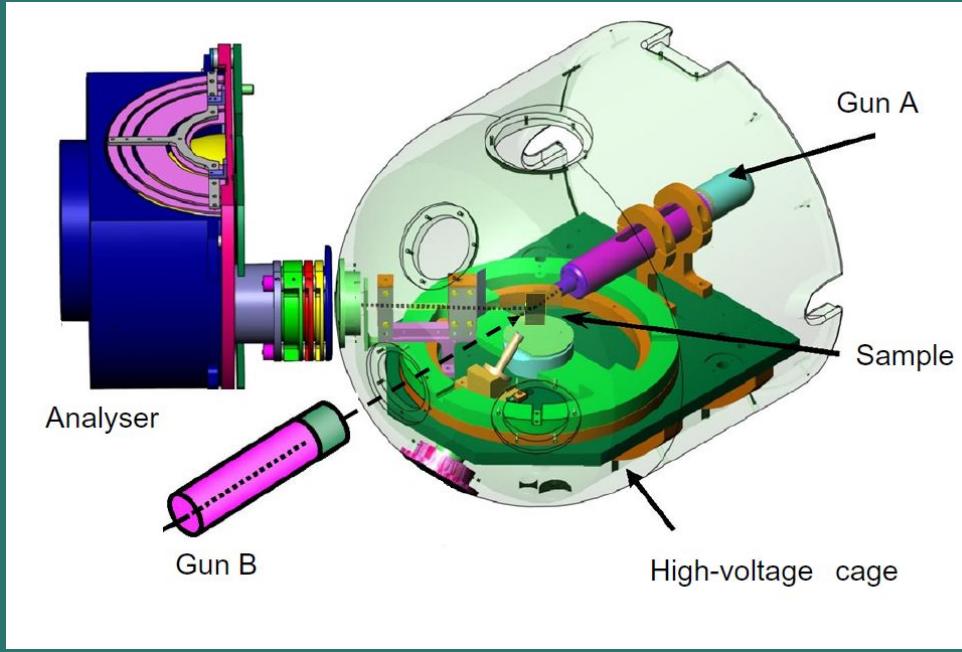
$$E_r \propto E_0$$

$$\sigma \propto (E_{kin})^{\frac{1}{2}}$$



# ERBS system at ANU

- 500 eV e-gun
- 40 keV electrons
- High voltage cage
- Hemispherical analyser  
with  $\sim 0.35$  eV resolution
- $135^\circ$  scattering angle



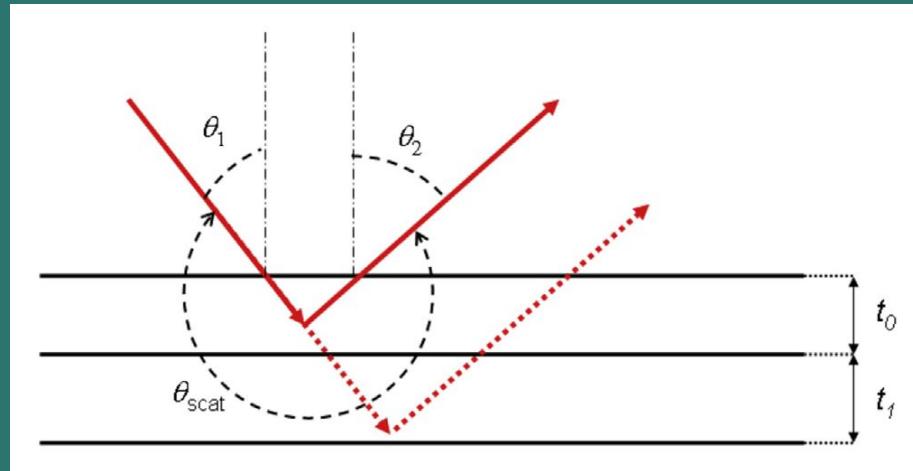
# 2. ERBS analysis

Fitting, thickness  
measurement,  
multiple scattering

# Fitting ERBS's spectra

- First layer contribution

$$I_{i,0} = \gamma C_{i,0} \sigma_i \lambda_0 \left( 1 - e^{-\frac{t_0}{(\cos \theta_1 + \cos \theta_2) \lambda_0}} \right)$$

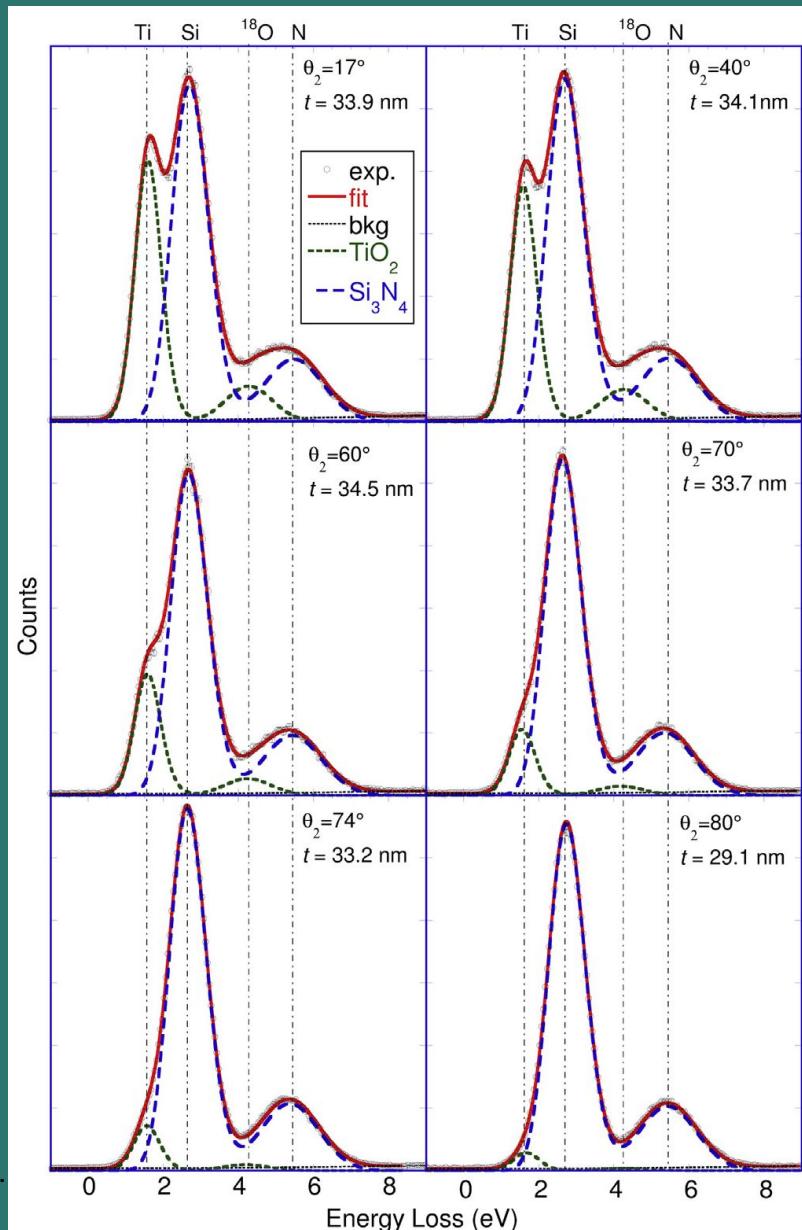
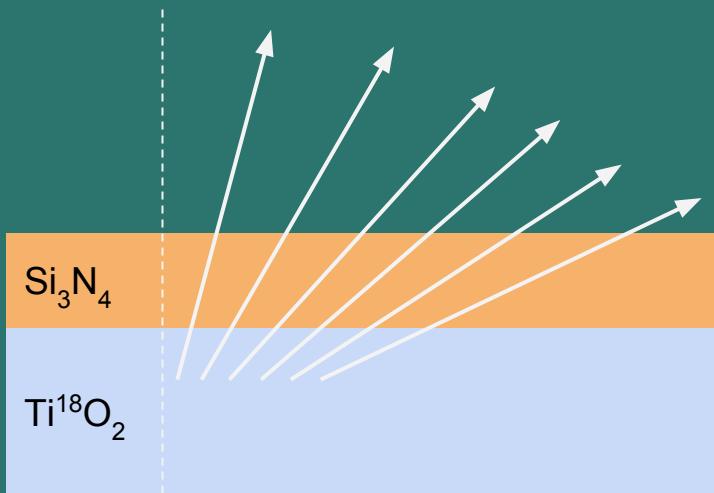


- Second layer contribution is attenuated

$$I_{i,1} = \gamma C_{i,1} \sigma_i \lambda_1 \left( 1 - e^{-\frac{t_1}{(\cos \theta_1 + \cos \theta_2) \lambda_1}} \right) e^{-\frac{t_0}{(\cos \theta_1 + \cos \theta_2) \lambda_0}}$$

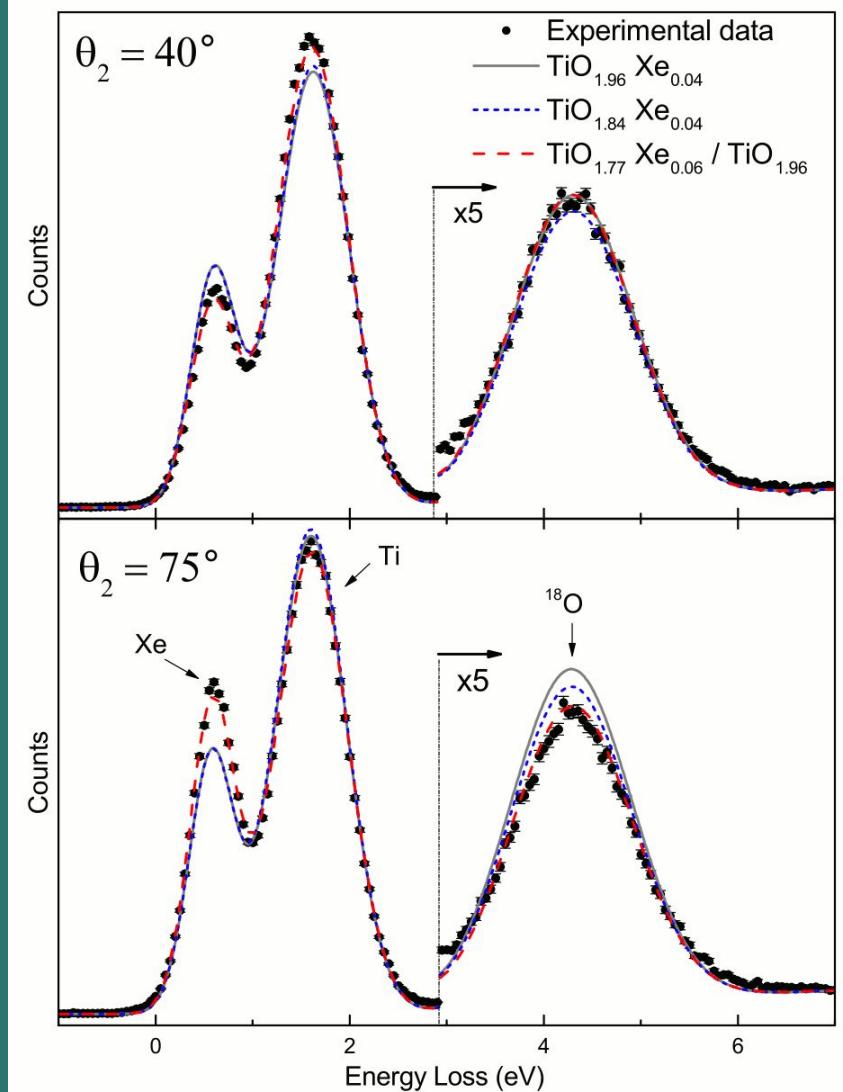
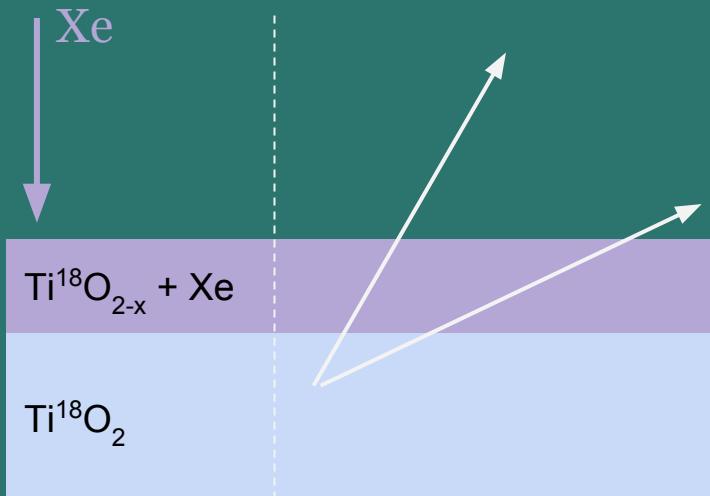
# Thickness measurements

- Exit angle: 17 to 80°
- Displacement → attenuation



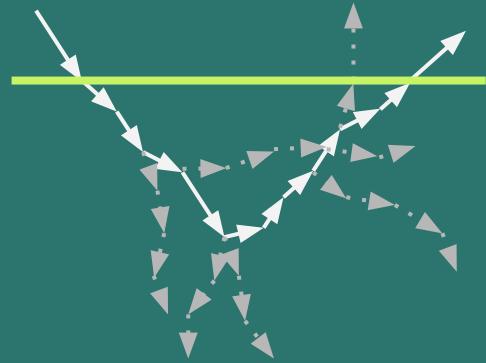
# Thickness measurements

- Xe sputtering in  $\text{TiO}_2$
- Simultaneous fitting
- Preferential sputtering of O

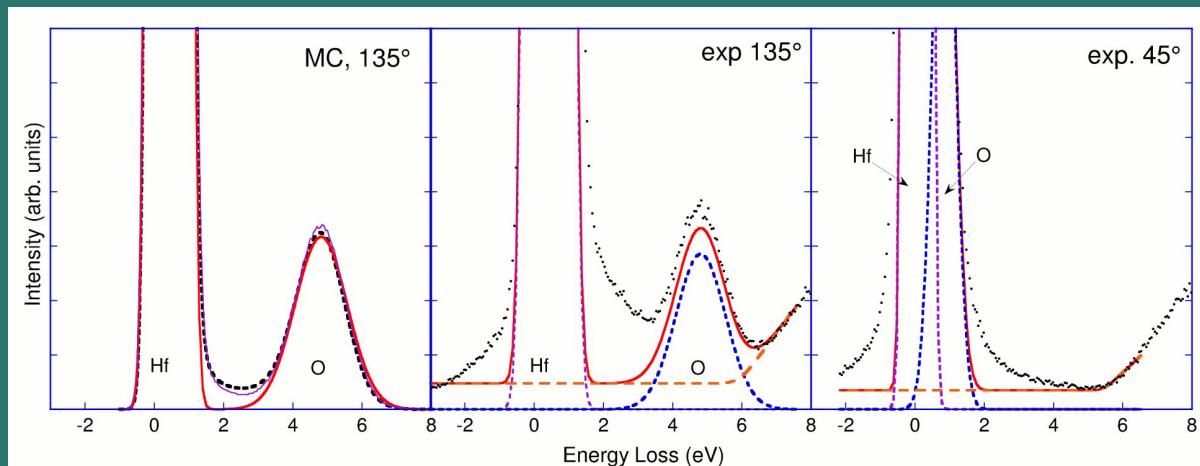
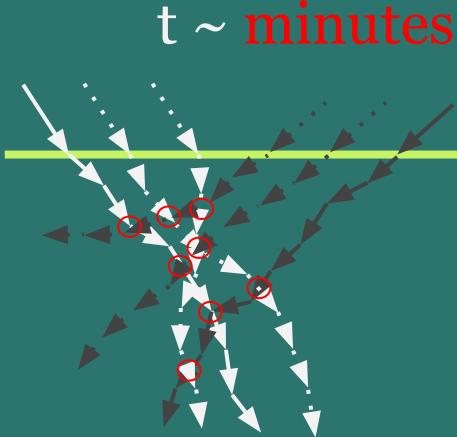


# Multiple scattering

MC direct trajectories  
 $t \sim$  days



MC connected trajectories  
 $t \sim$  minutes



# 3. O diffusion in TiO<sub>2</sub>

Memristors, sample  
preparation, results

# TiO<sub>2</sub> Memristor

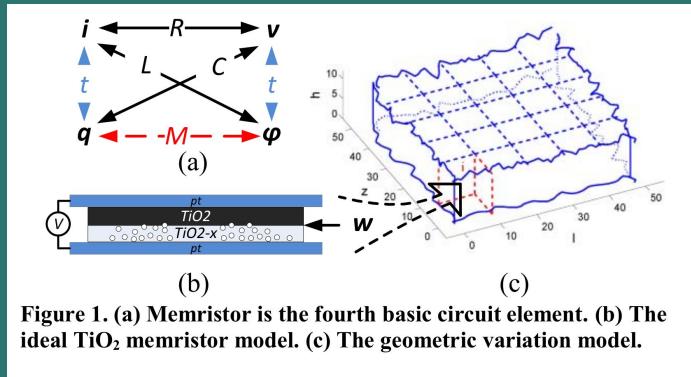
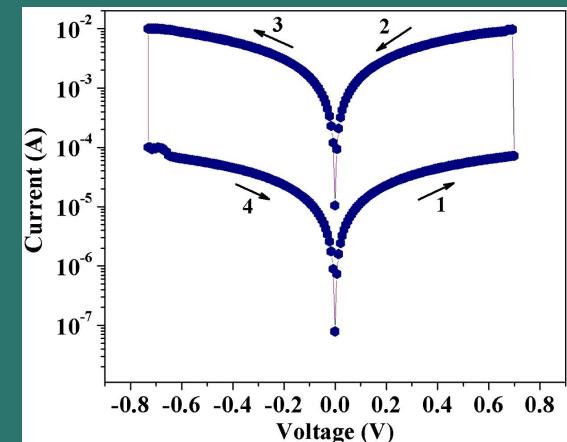
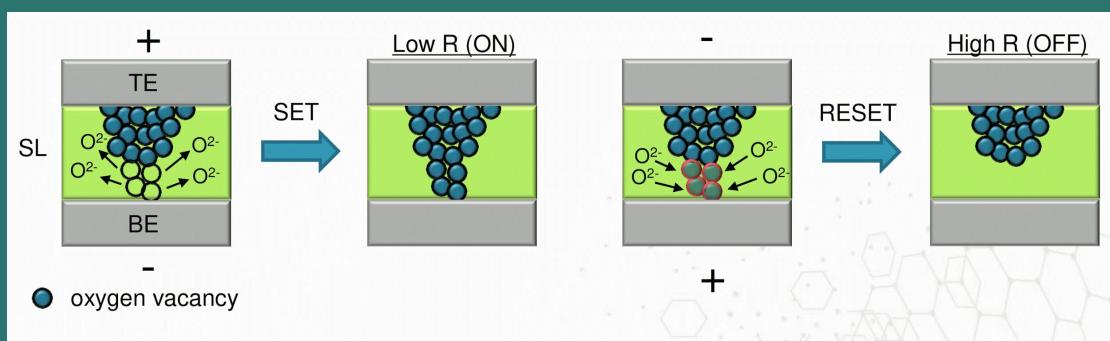
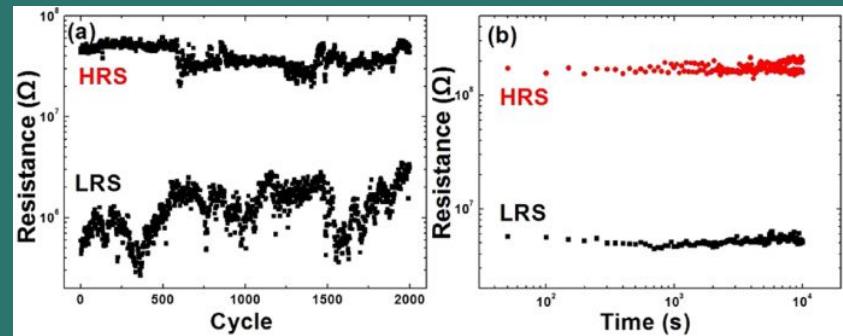
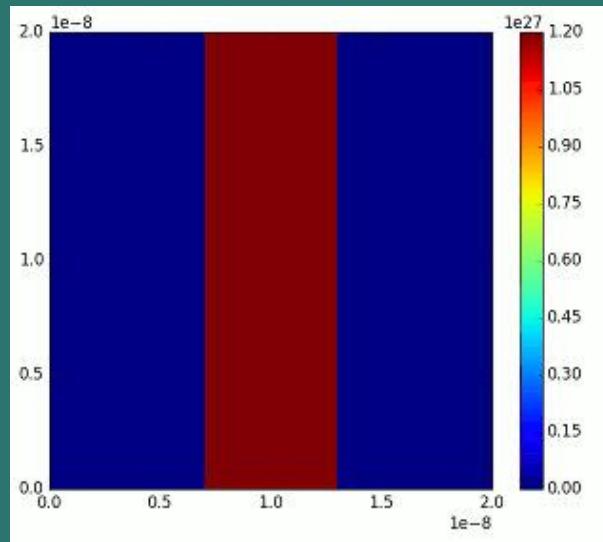


Figure 1. (a) Memristor is the fourth basic circuit element. (b) The ideal TiO<sub>2</sub> memristor model. (c) The geometric variation model.

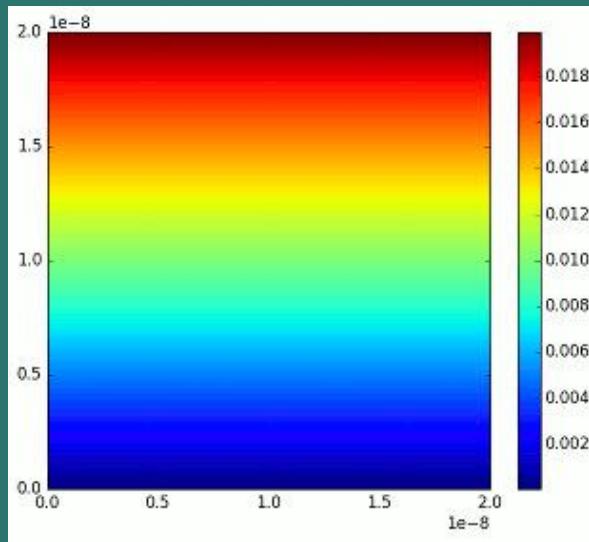


# Bipolar switching model

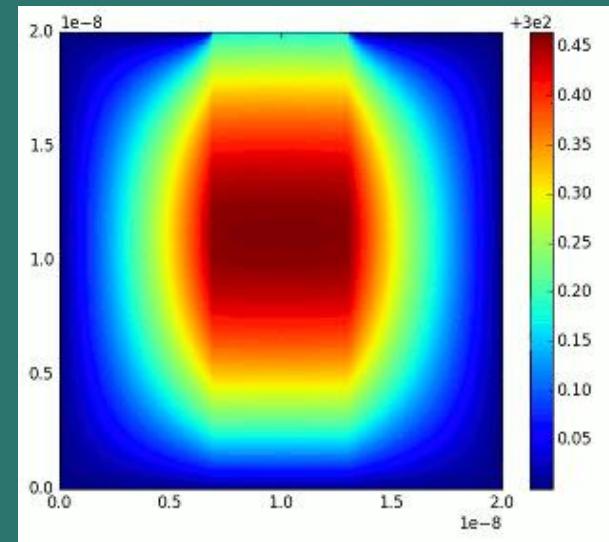
O vacancies



Electric potential



Temperature



$$\frac{\partial n_D}{\partial t} = \nabla \cdot (D \nabla n_D - \mu F n_D).$$

$$\nabla \cdot \sigma \nabla \psi = 0$$

$$-\nabla \cdot k_{\text{th}} \nabla T = \sigma |\nabla \psi(r, z)|^2$$

$$D = D_0 e^{-\frac{E_A}{kT}}$$

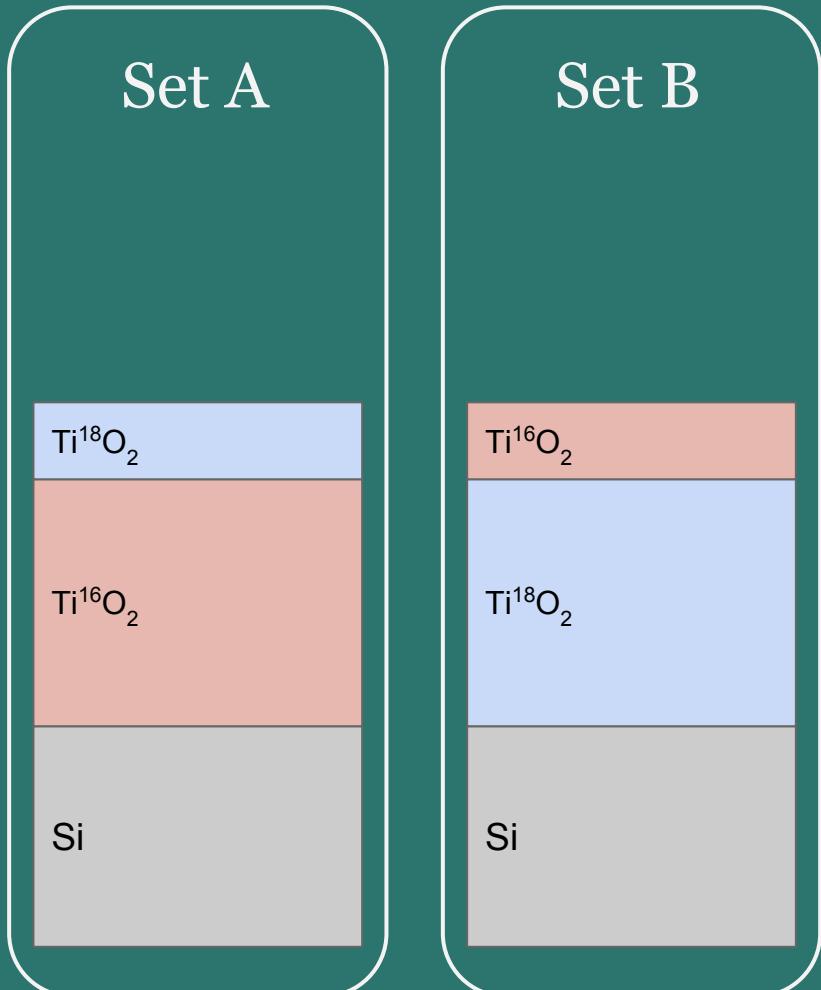
$$\mu = \frac{qD}{kT}.$$

$$\sigma = \sigma_0 e^{-\frac{E_{\text{AC}}}{kT}}$$

$$k_{\text{HfO}} = k_{\text{HfO}_0} (1 + \lambda(T - T_0))$$

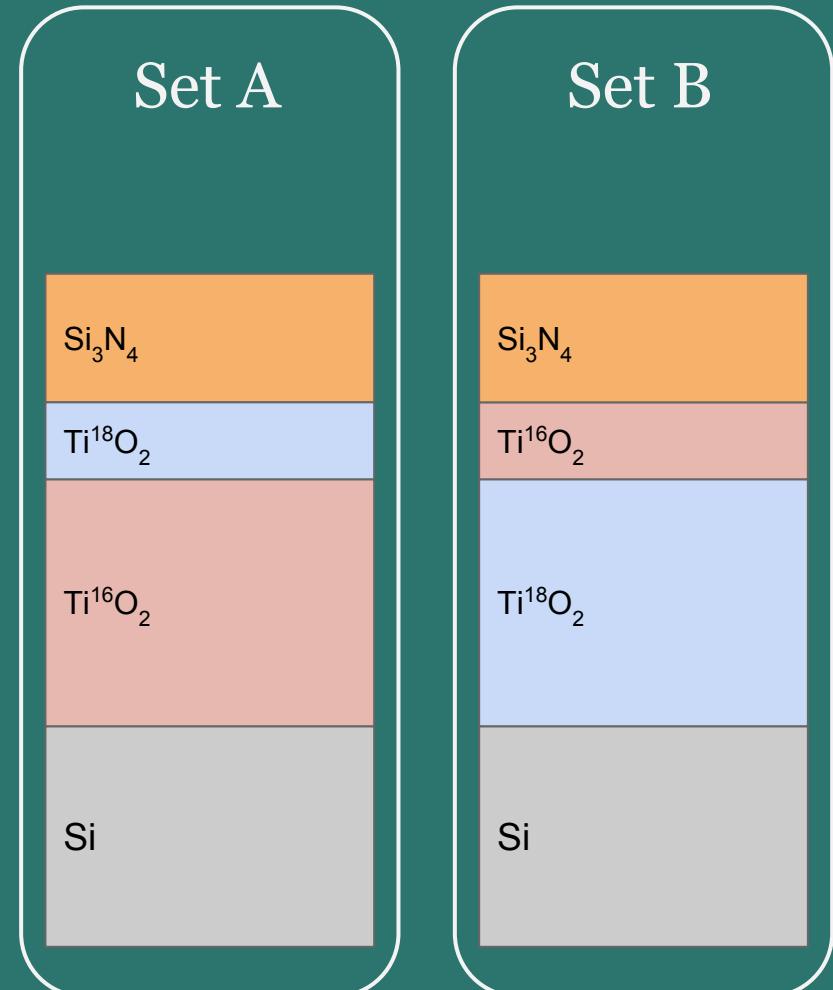
# Sample preparation

- Depositions (Set A)
  - 60 nm  $\text{Ti}^{16}\text{O}_2$
  - 20 nm  $\text{Ti}^{18}\text{O}_2$
- Inverted sample (Set B)
- Capping layer
- Thermal annealing in Ar
  - 5 - 100 min
  - 500 - 900°C
- HF chemical etching



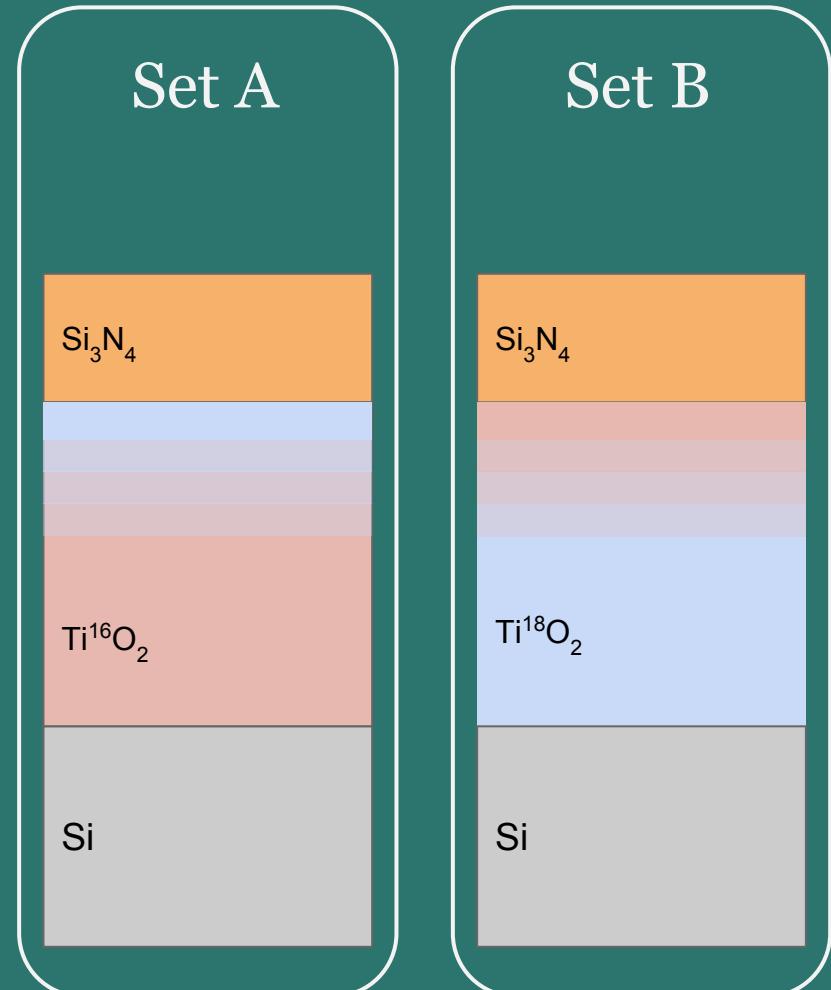
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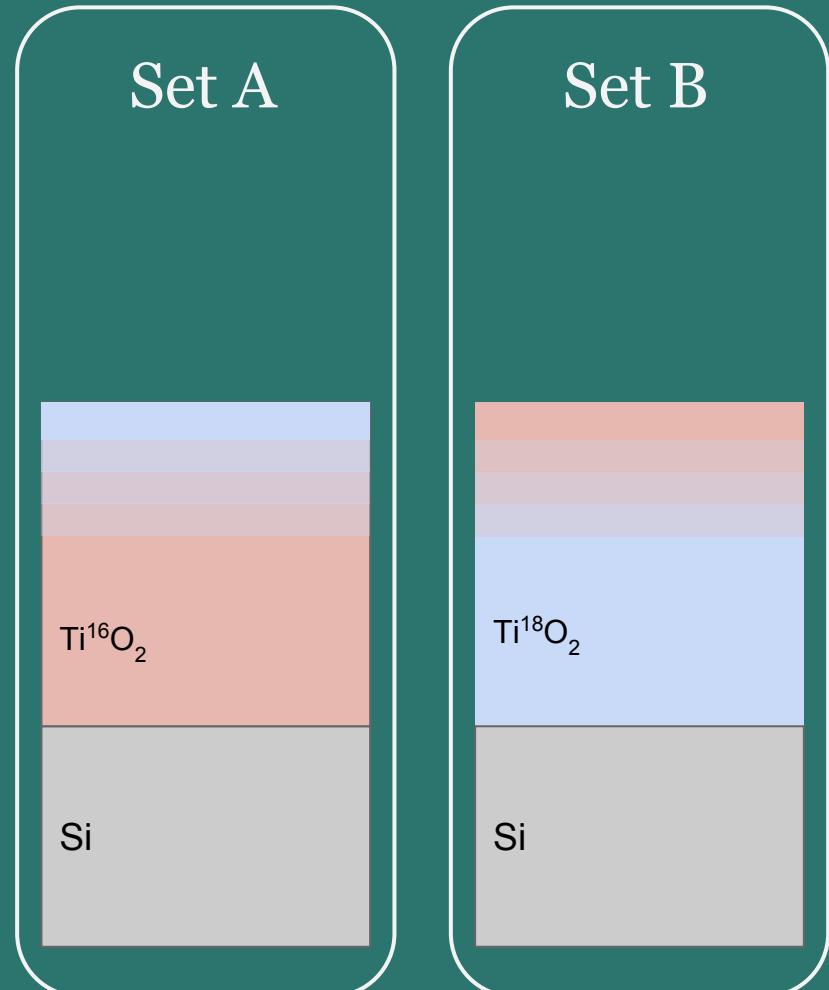
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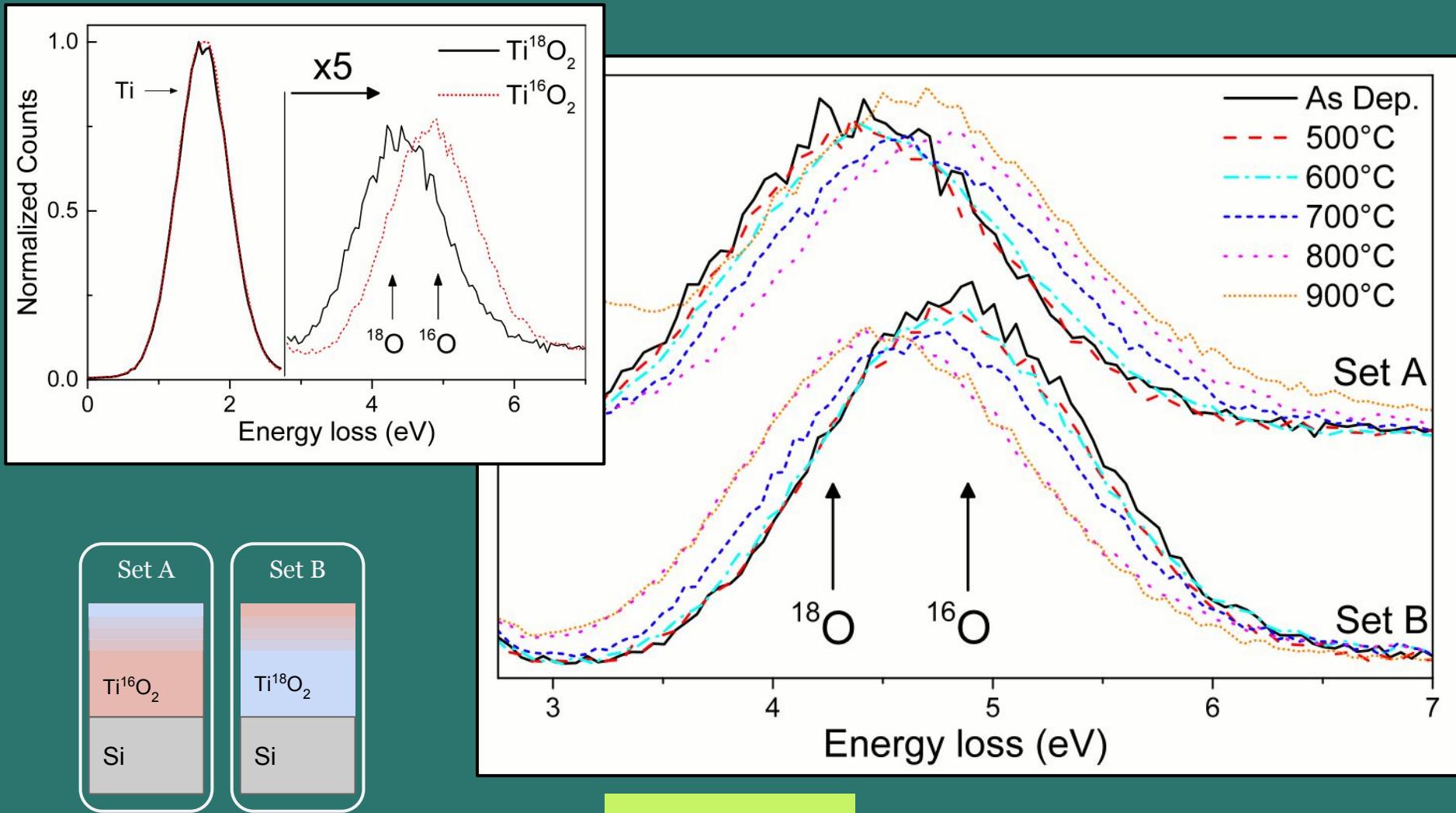


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# ERBS measurements



40 keV electrons at glancing angles on both sets

# Diffusion profile

- Signal intensity

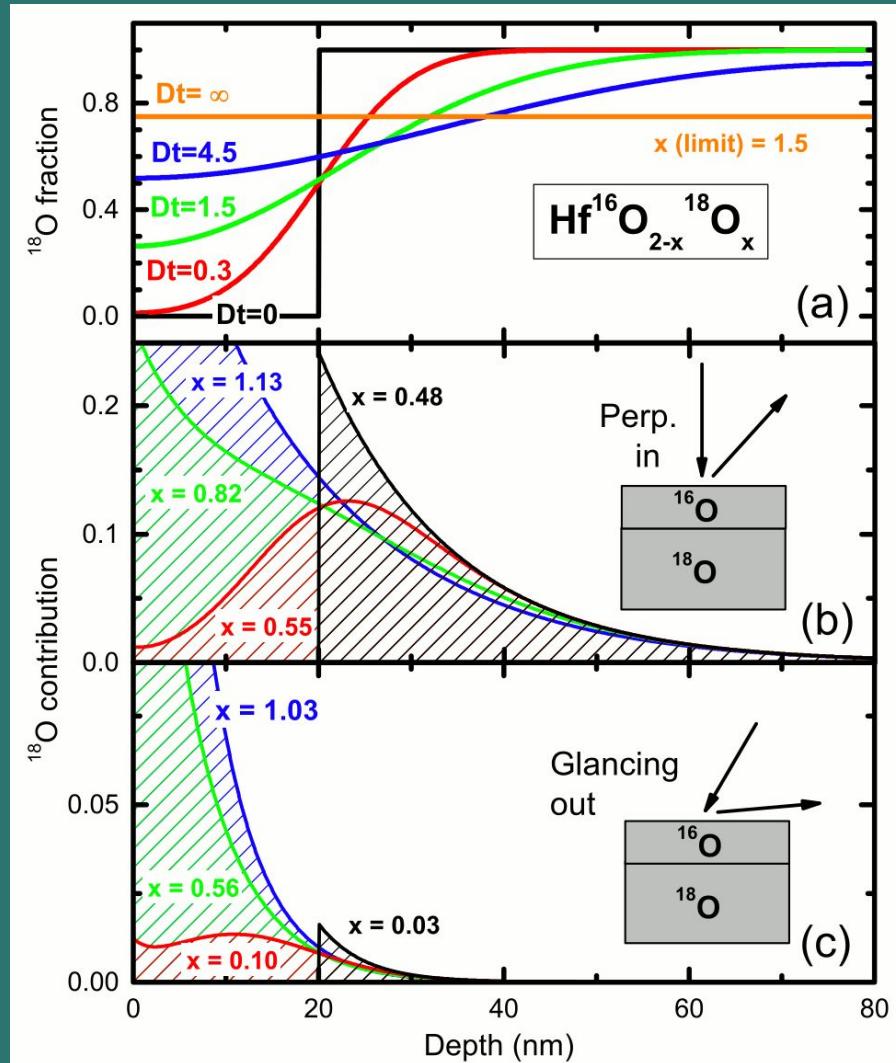
$$I(x) = I_0 e^{-l(x)/\lambda}$$

- Weighted sum

$$H_i = \sigma_i \int_0^\infty I(x) \phi_i(x) dx$$

- Diffusion equation

$$\frac{\partial \phi_i}{\partial t} = D \nabla^2 \phi_i$$



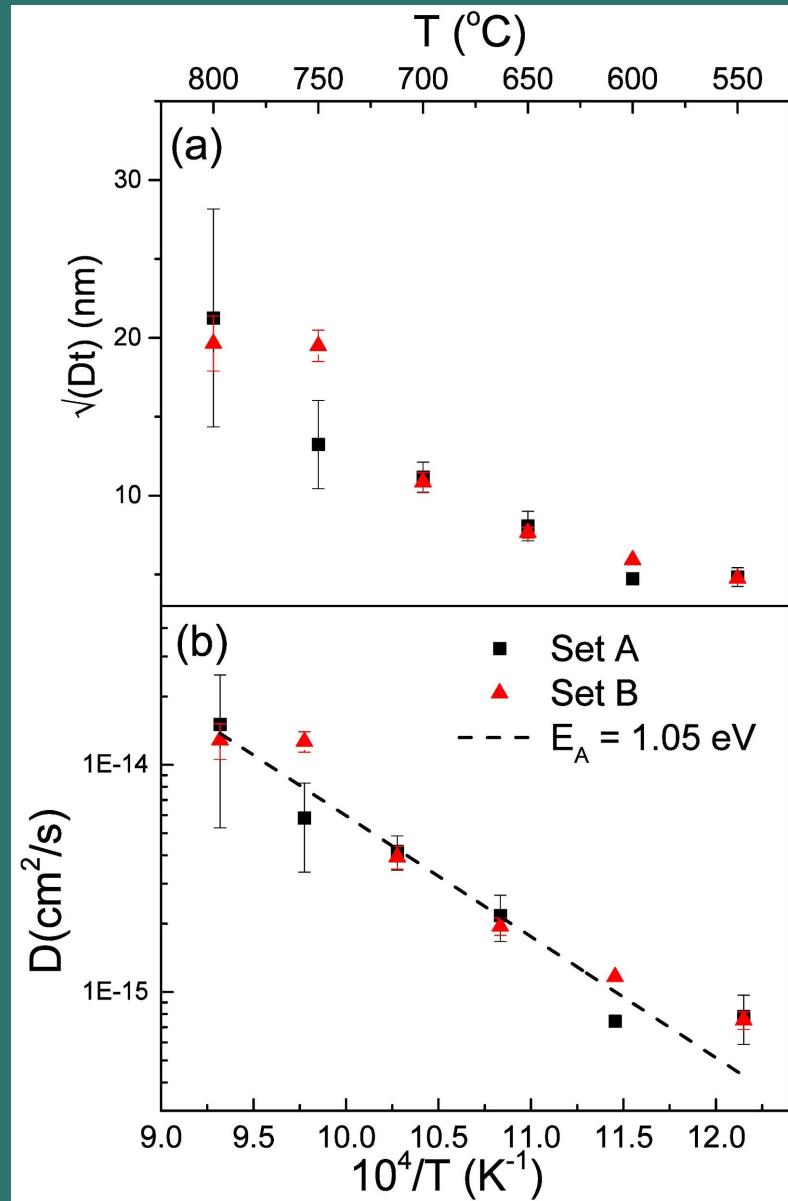
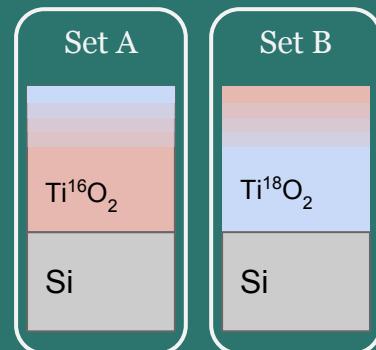
# Activation energy

- ERBS spectra fitted with diffusion profiles
- Initial  $^{18}\text{O}$  concentration

Slope  $\rightarrow E_A$  for O diffusion in  $\text{TiO}_2$

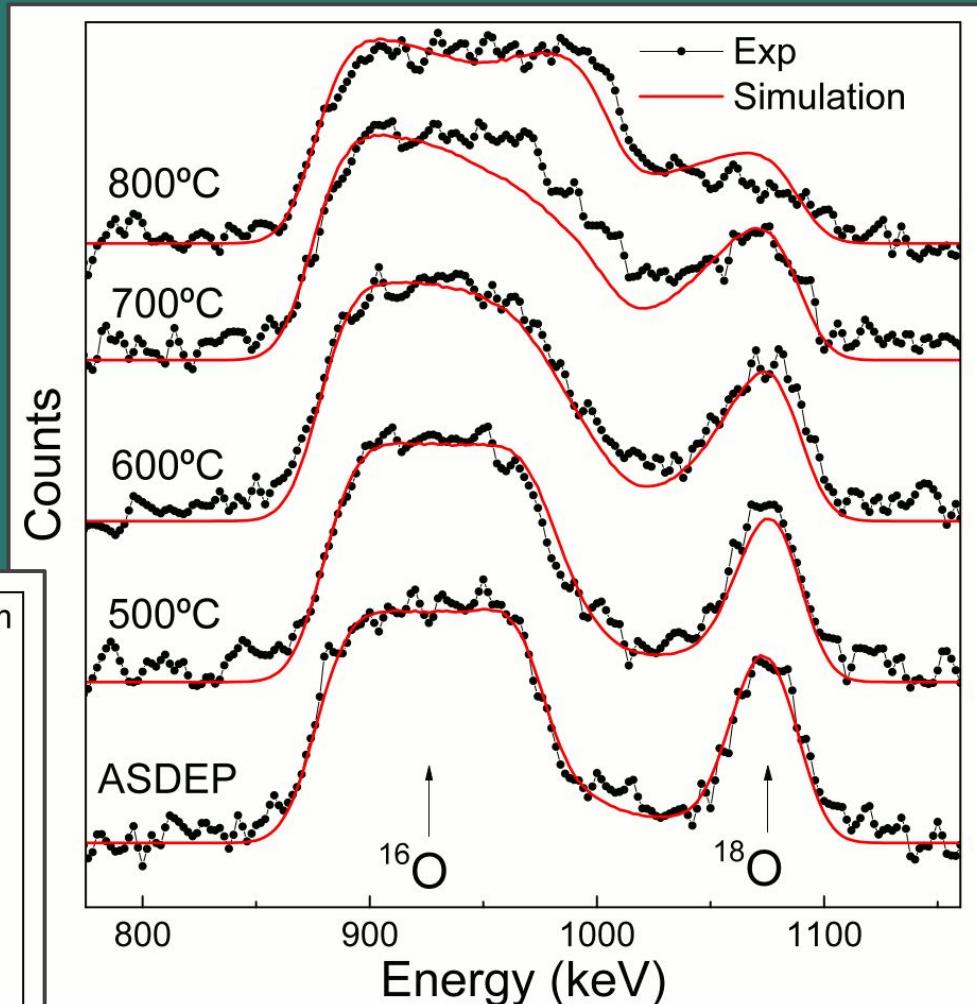
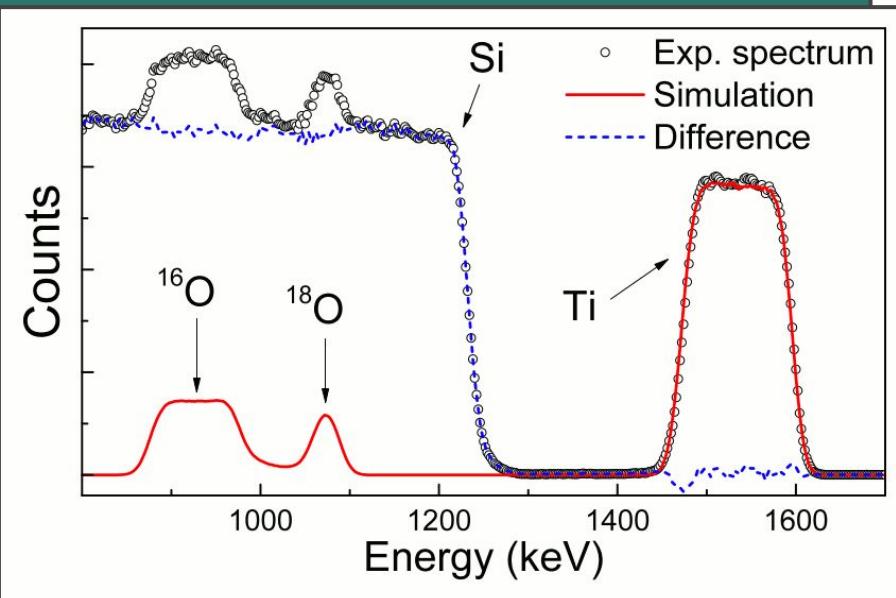
$$D = D_0 e^{-\frac{E_a}{kT}}$$

$$\ln(D) = \ln(D_0) - \frac{E_a}{k} \frac{1}{T}$$



# RBS measurements

- 2 MeV He<sup>+</sup>
- Only on  $^{18}\text{O}$  /  $^{16}\text{O}$  / Si
- PowerMEIS simulations
- ERBS's determined profiles



# 4. Conclusions

Discussion,  
perspectives

# Discussion & perspectives

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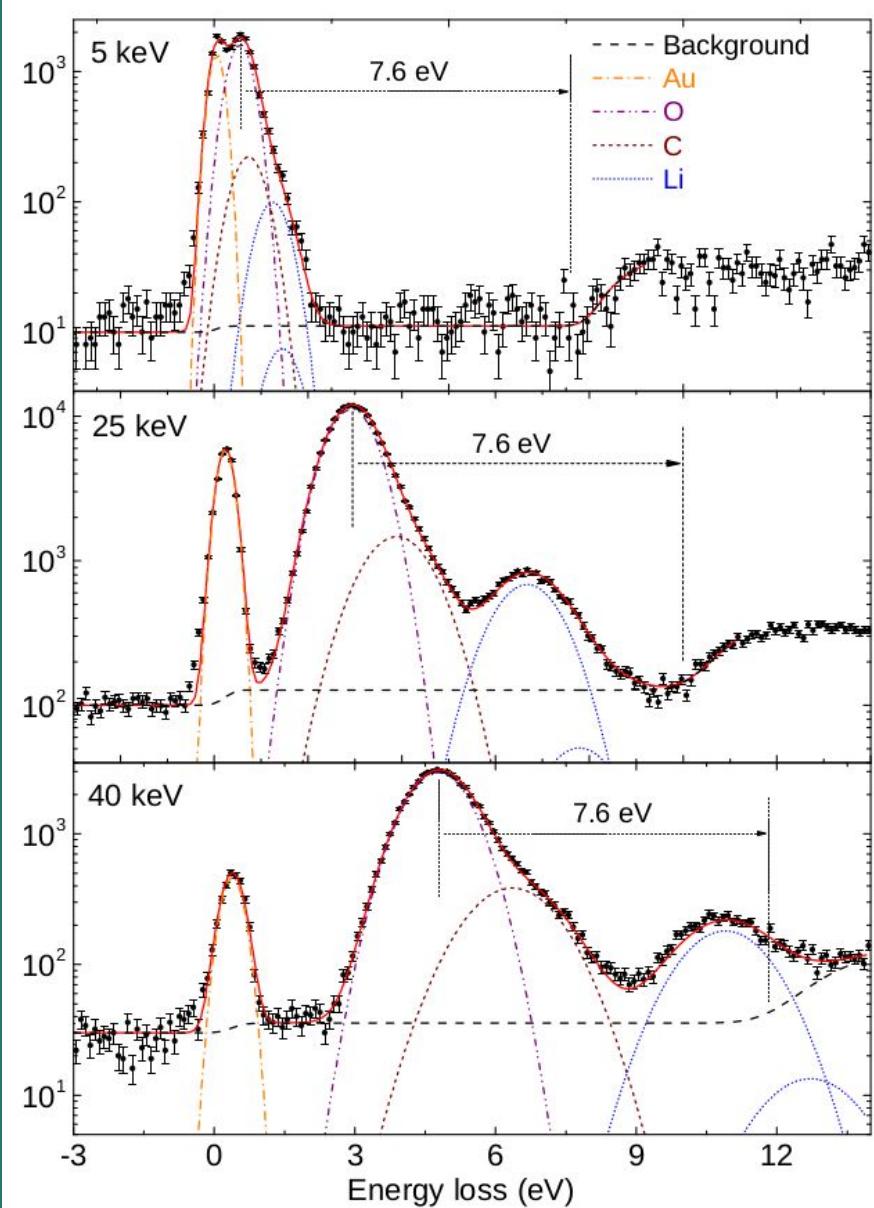
- ERBS spectra have similarities to RBS and XPS
- Analysis can extract stoichiometry and thickness
- The activation energy of O diffusion in TiO<sub>2</sub> was measured at 1.05 eV
- We are building RRAM devices to further study the formation of the filaments

# thanks!



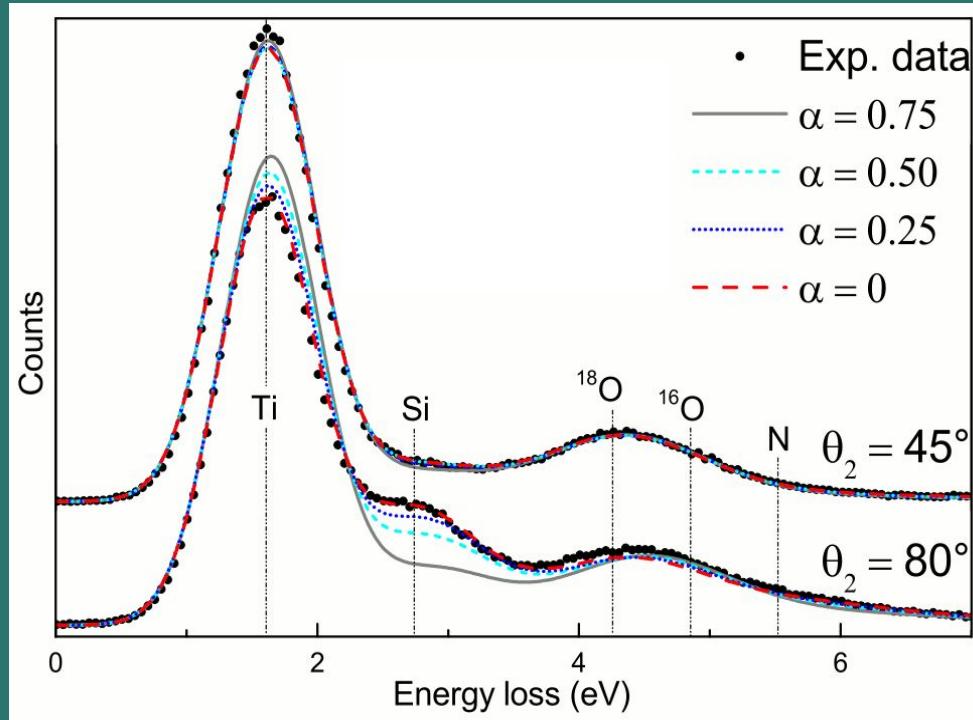
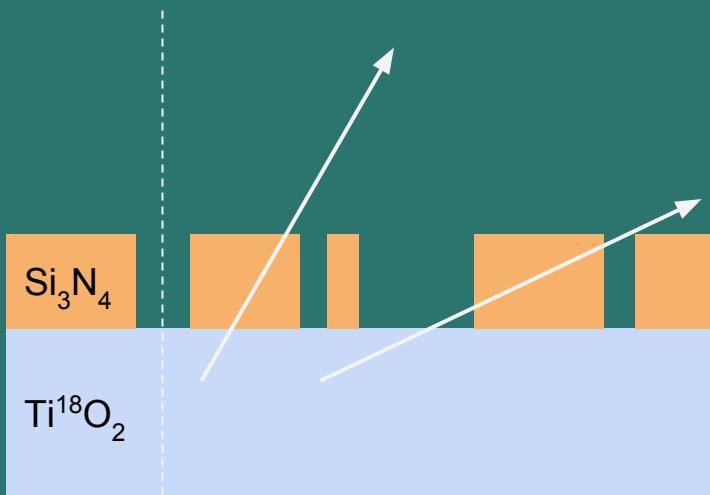
# Bandgap

- Au / Li<sub>2</sub>CO<sub>3</sub>
- Fixed geometry
- Energy: 5 to 40 keV
  
- Simultaneous fitting
- Background → bandgap



# Thickness measurements

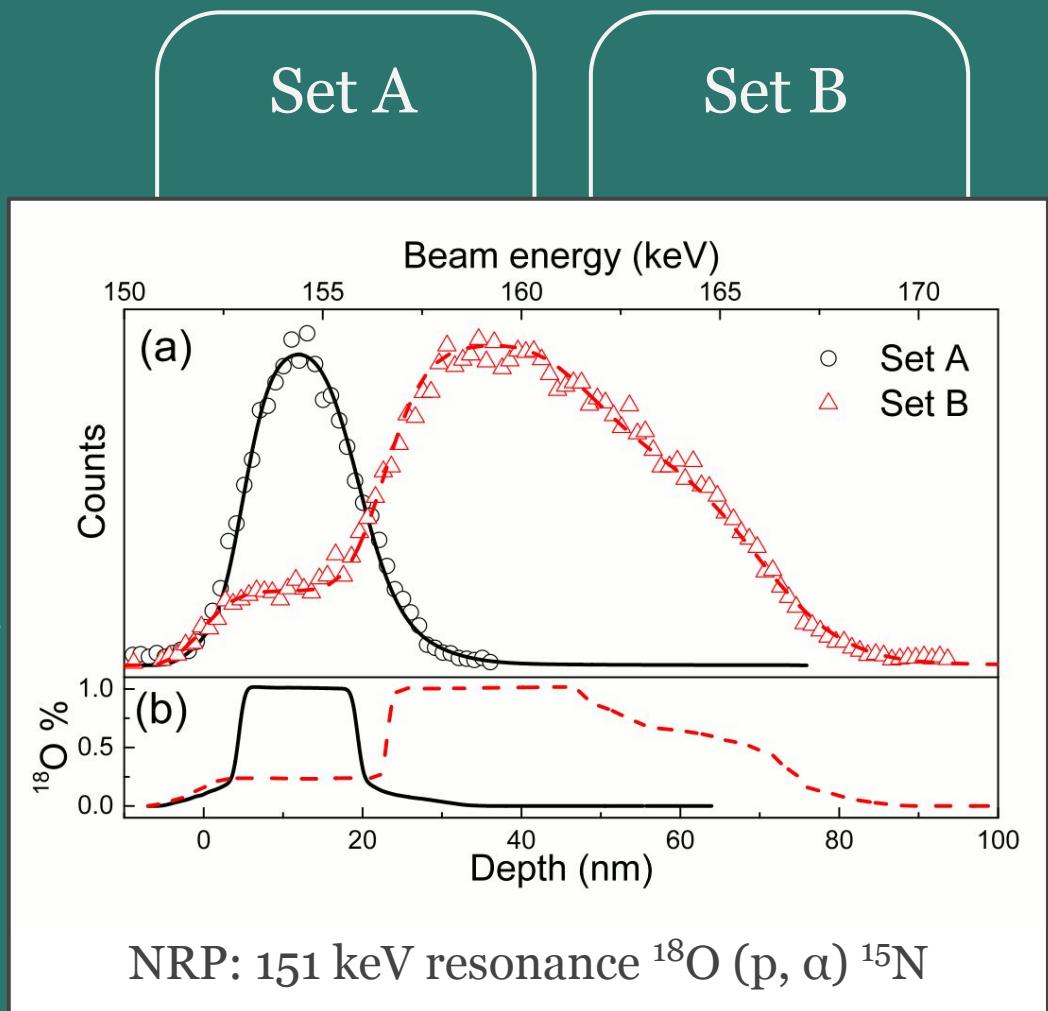
- Scatt. angle: 135°
- $\text{Si}_3\text{N}_4$  islands?



$$\alpha = 1 - \frac{A_{\text{Si}_3\text{N}_4}}{A_{\text{total}}}$$

# Sample preparation

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- HF chemical etching



# Diffusion irregularity

Our measurements  
 $500 \text{ }^{\circ}\text{C} < T < 800 \text{ }^{\circ}\text{C}$   
 $t = 5 \text{ min}$   
 $E_A \sim 1.05 \text{ eV}$

Arita et al.  
 $T > 1000 \text{ }^{\circ}\text{C}$   
 $t > 20 \text{ h}$   
 $E_A \sim 3 \text{ eV}$

